

PAT-NO: JP410133597A
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TITLE: WIRING BOARD, PRODUCTION OF THIS WIRING BOARD,
LIQUID CRYSTAL ELEMENT HAVING THIS WIRING BOARD AND
PRODUCTION OF LIQUID CRYSTAL ELEMENT
PUBN-DATE: May 22, 1998

INVENTOR-INFORMATION:

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ABSTRACT:

PROBLEM TO BE SOLVED: To improve the adhesion between metallic electrodes and a glass substrate and to prevent corrosion by the oxidation of these metallic electrodes.

SOLUTION: The metallic electrodes 3 consisting of copper nitride having a nitrogen content of 0.1 to 50at.%, more preferably 1 to 10at.% are patterned as wirings and are formed on the glass substrate 2. The wiring board 1 is formed by embedding a UV curing resin 4 between the metallic electrodes 3 to

flatten
the surface, by which the adhesion property between the glass
substrate 2 and
the metallic electrodes 3 is improved and the corrosion by the
oxidation of the
metallic electrodes 3 is prevented.

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